Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	24	("4804810" "4944447" "4986460" "5087590" "5188280" "5297333" "5427301" "5628110" "5648136" "5988481" "6013899" "6029427" "6053234" "6070780" "6092713" "6100496" "6131795" "6146920" "6158648" "6168669" "6182733" "6193459" "6226452" "6543131").PN. OR ("6818543").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/07 14:38
S1	6	"bottner, harald".in. and "schubert, axel".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 09:28
S2	6	(("6319617") or ("5320272") or ("4636073")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/13 09:48
S 3	514	(257/772).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/13 15:35
S4	589	solder and eutectic and gold and bismuth	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/07 10:08
S5	33	eutectic with (gold with bismuth)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 13:19
S6	154	peltier and eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 13:31

				00	011	2005/07/42 42 21
S7	434	"laser diode" and eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 13:31
S8	78	(interdigitated same capacitor) and humidity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/07/13 16:00
S9	234	"heat sink" with eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 15:12
S10	23	"photodiode" with eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 15:22
S11	0	"fluid cell" with eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 15:23
S12	1	"fluidic cell" and eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 15:24
S13	1	"fluidic cell" and solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 15:24
S14	39	"fluidic cell"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 15:35

S15	35	(interdigitated same (capacitor or electrode)) and humidity and (solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/07/13 16:08
S16	2279	humidity near2 (sensor or sens\$3) and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 16:08
S17	98	humidity near2 (sensor or sens\$3) and substrate and interdigitated	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/13 16:09
S18	2	("5072262" "5546802").PN. OR ("6568265").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 16:19
S19	6	"fluidic cell" and peltier .	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/13 16:20

S20	44	(US-20010037681-\$ or US-20020024662-\$ or US-20020100972-\$ or	US-PGPUB; USPAT	OR	ON	2005/09/07 10:00
		US-20020179135-\$ or US-20030056571-\$ or	Ì			
		US-20030056371-3 01 US-20030075939-\$ or				
		US-20030127333-\$ or				
		US-20030127333-\$ 01 US-20030202332-\$ or				
		US-20030202332-\$ 01 US-20040046223-\$ or				
		US-20040046223-\$ 01 US-20040067604-\$ or				
		US-20040087804-5 07				·
		US-20040188813-\$ or				
		US-20040100813-3 01 US-20040212094-\$ or				
		US-20040212034-5 01 US-20040238966-\$ or				
		US-20040236900-5 07				
		US-20050110157-\$ or				
		US-20050110137-\$ 01 US-20050133572-\$).did. or				
		(US-3607148-\$ or US-4651191-\$ or				
		US-4915167-\$ or US-4947238-\$ or				
		US-5040381-\$ or US-5542018-\$ or				
		US-5596231-\$ or US-5736074-\$ or				
		US-5854087-\$ or US-5966939-\$ or				
		US-6077380-\$ or US-6108472-\$ or				
		US-6153940-\$ or US-6159764-\$ or				
		US-6281573-\$ or US-6327407-\$ or				
		US-6344690-\$ or US-6455785-\$ or				
		US-6486411-\$ or US-6548750-\$ or				
		US-6550665-\$ or US-6568265-\$ or				
		US-6680128-\$ or US-6740544-\$ or				·
		US-6774306-\$ or US-6786385-\$).				
		did. or (US-6818543-\$).did.				
S21	25	S20 and gold and bismuth	US-PGPUB;	OR	ON	2005/09/07 10:00
022		Cao ana gona ana disina	USPAT			,,
622	500			00	ON	2005/00/07 10:00
S22	599	solder and eutectic and gold and	US-PGPUB;	OR	ON	2005/09/07 10:08
		bismuth	USPAT;			
			USOCR; EPO; JPO;			
			DERWENT;			
			IBM_TDB			
			_	:		
S23	364	S22 and (layer with (thickness or	US-PGPUB;	OR	ON	2005/09/07 10:09
		thick))	USPAT;			
	-		USOCR;			
			EPO; JPO;			
			DERWENT;			
			IBM_TDB			
S24	127	S22 and (solder with layer with	US-PGPUB;	OR	ON ·	2005/09/07 10:09
:	1	(thickness or thick))	USPAT;		•	
		, "	USOCR;			
			EPO; JPO;			
			DERWENT;			
			IBM_TDB			